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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	4250
Number of Logic Elements/Cells	34000
Total RAM Bits	2151424
Number of I/O	410
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m35se-5fn672c

Figure 2-1. Simplified Block Diagram, ECP2-6 Device (Top Level)

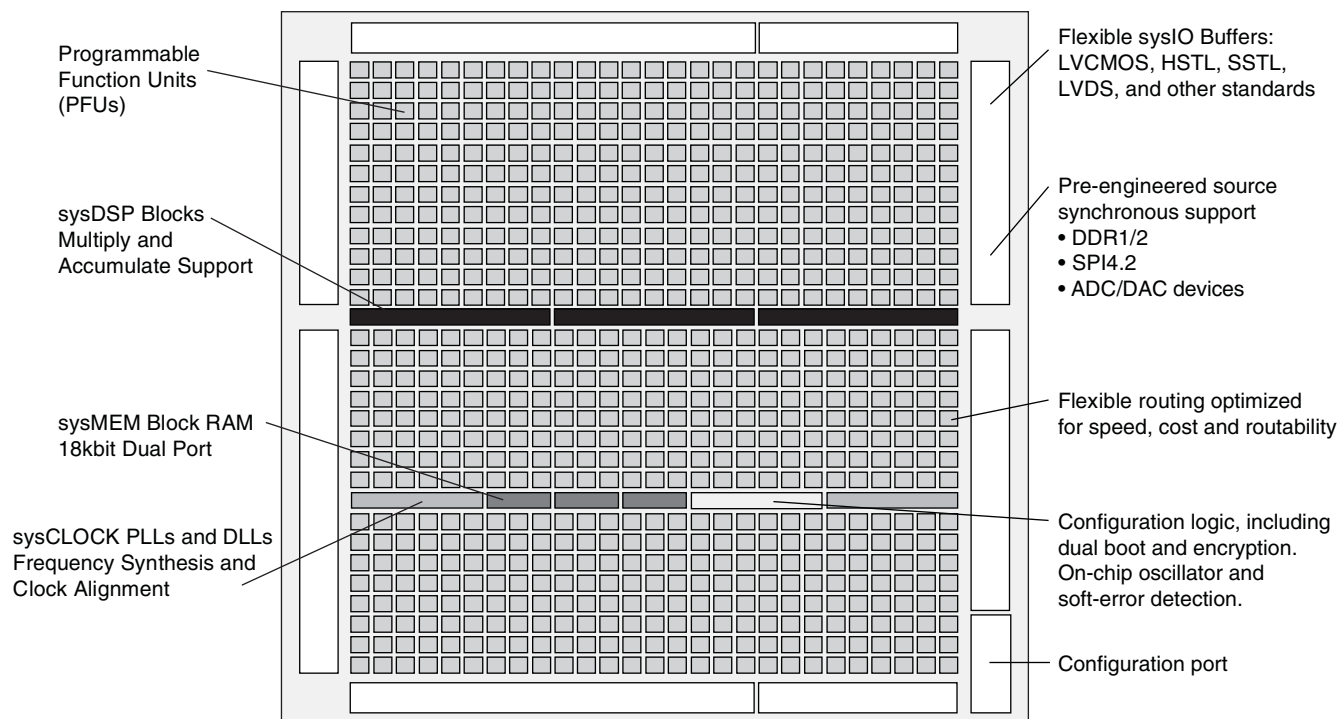


Figure 2-2. Simplified Block Diagram, ECP2M20 Device (Top Level)

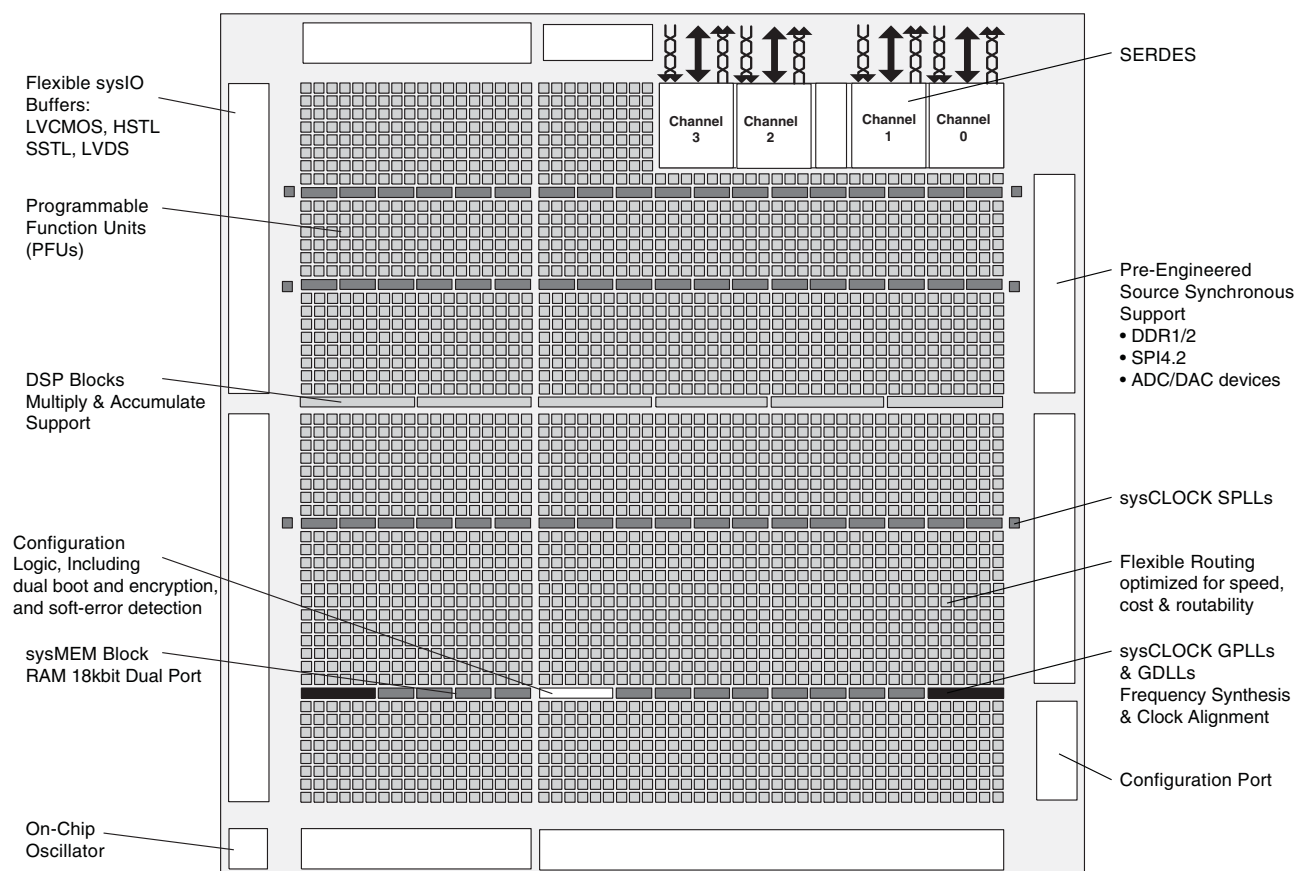
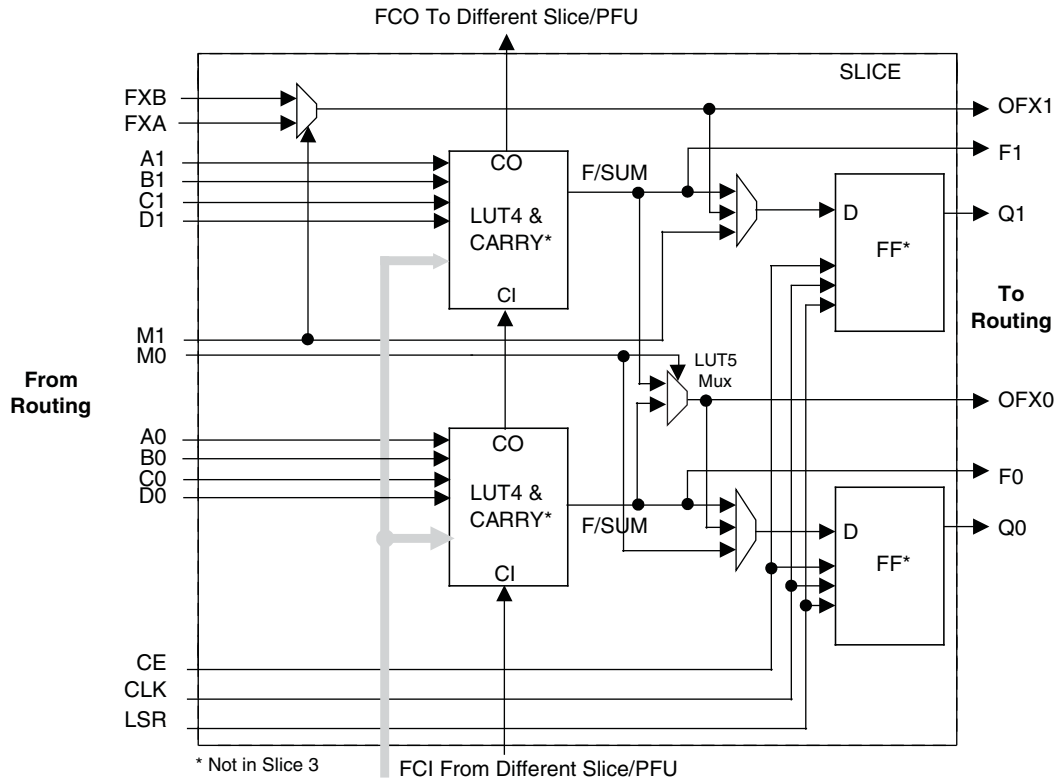


Figure 2-4. Slice Diagram



For Slices 0 and 2, memory control signals are generated from Slice 1 as follows:

WCK is CLK
WRE is from LSR
DI[3:2] for Slice 2 and DI[1:0] for Slice 0 data
WAD [A:D] is a 4bit address from slice 1 LUT input

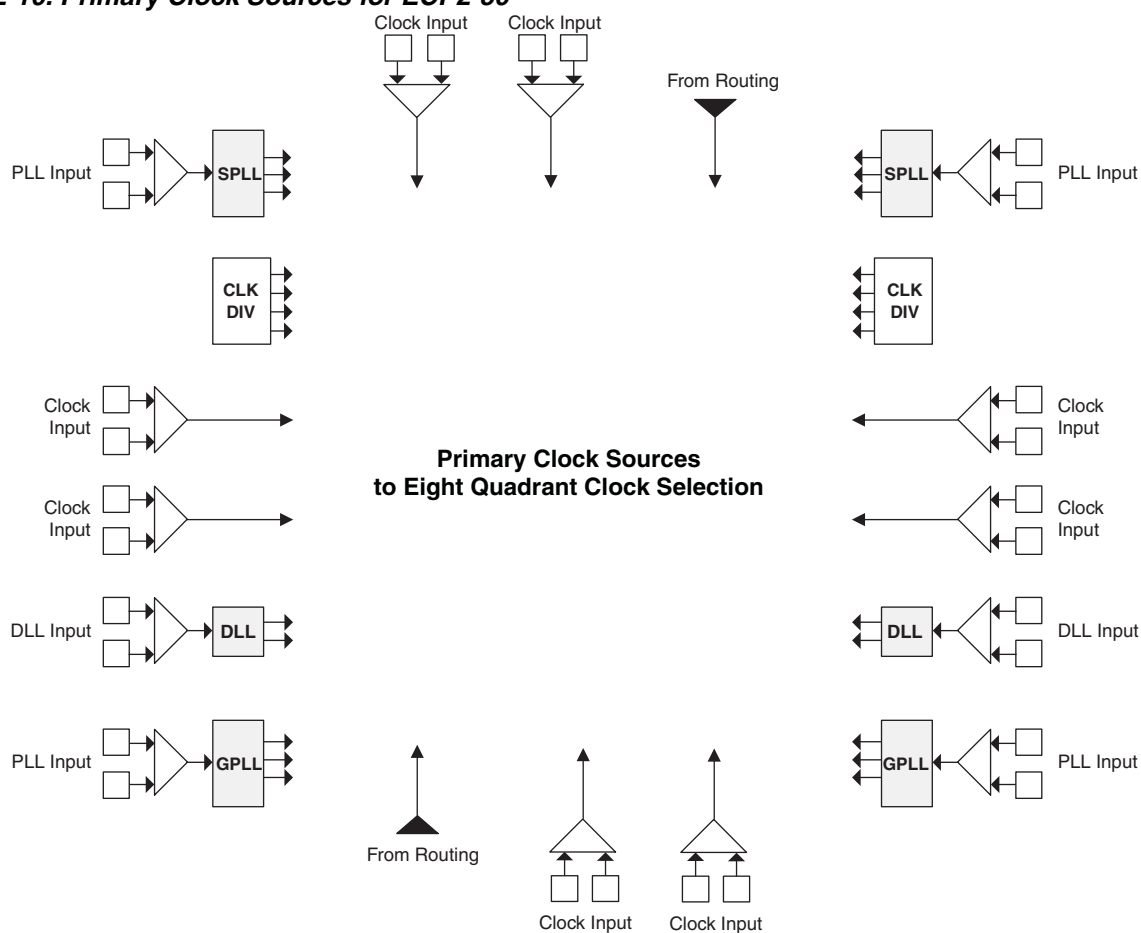
Table 2-2. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FC	Fast Carry-in ¹
Input	Inter-slice signal	FXA	Intermediate signal to generate LUT6 and LUT7
Input	Inter-slice signal	FXB	Intermediate signal to generate LUT6 and LUT7
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8 ² MUX depending on the slice
Output	Inter-PFU signal	FCO	Slice 2 of each PFU is the fast carry chain output ¹

1. See Figure 2-4 for connection details.

2. Requires two PFUs.

Figure 2-10. Primary Clock Sources for ECP2-50



Note: This diagram shows sources for the ECP2-50 device. Smaller LatticeECP2 devices have fewer SPLLs. All LatticeECP2M devices have six SPLLs.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

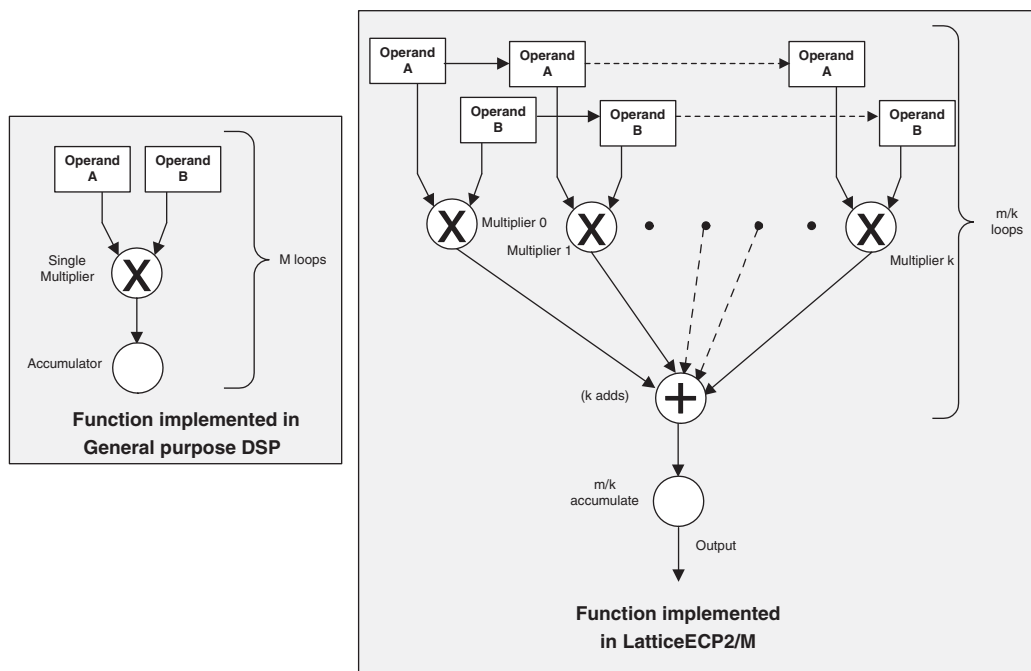
sysDSP™ Block

The LatticeECP2/M family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP2/M, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-22 compares the fully serial and the mixed parallel and serial implementations.

Figure 2-22. Comparison of General DSP and LatticeECP2/M Approaches



sysDSP Block Capabilities

The sysDSP block in the LatticeECP2/M family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP2/M family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block. In the LatticeECP2/M family the DSP elements can be concatenated.

The resources in each sysDSP block can be configured to support the following elements:

Table 2-12. PIO Signals List

Name	Type	Description
CE0, CE1	Control from the core	Clock enables for input and output block flip-flops
CLK0, CLK1	Control from the core	System clocks for input and output blocks
ECLK1, ECLK2	Control from the core	Fast edge clocks
LSR	Control from the core	Local Set/Reset
GSRN	Control from routing	Global Set/Reset (active low)
INCK ²	Input to the core	Input to Primary Clock Network or PLL reference inputs
DQS	Input to PIO	DQS signal from logic (routing) to PIO
INDD	Input to the core	Unregistered data input to core
INFF	Input to the core	Registered input on positive edge of the clock (CLK0)
IPOS0, IPOS1	Input to the core	Double data rate registered inputs to the core
QPOS0 ¹ , QPOS1 ¹	Input to the core	Gearbox pipelined inputs to the core
QNEG0 ¹ , QNEG1 ¹	Input to the core	Gearbox pipelined inputs to the core
OPOS0, ONEG0, OPOS2, ONEG2	Output data from the core	Output signals from the core for SDR and DDR operation
OPOS1 ONEG1	Tristate control from the core	Signals to Tristate Register block for DDR operation
DEL[3:0]	Control from the core	Dynamic input delay control bits
TD	Tristate control from the core	Tristate signal from the core used in SDR operation
DDRCLKPOL	Control from clock polarity bus	Controls the polarity of the clock (CLK0) that feed the DDR input block
DQSXFER	Control from core	Controls signal to the Output block

1. Signals available on left/right/bottom only.

2. Selected I/O.

PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

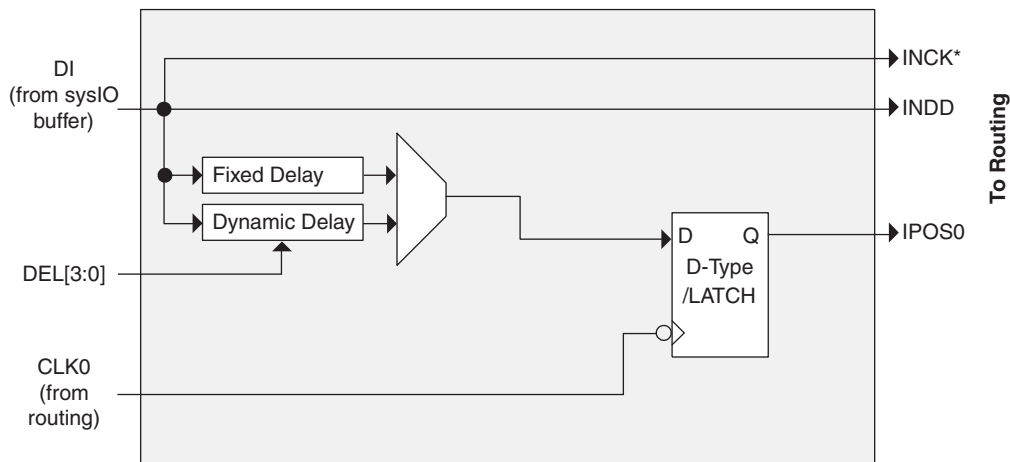
Input Register Block

The input register blocks for PIOs in left, right and bottom edges contain delay elements and registers that can be used to condition high-speed interface signals, such as DDR memory interfaces and source synchronous interfaces, before they are passed to the device core. Figure 2-29 shows the diagram of the input register block for left, right and bottom edges. The input register block for the top edge contains one memory element to register the input signal as shown in Figure 2-30. The following description applies to the input register block for PIOs in the left, right and bottom edges of the device.

Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired, the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and, in selected blocks, the input to the DQS delay block. If an input delay is desired, designers can select either a fixed delay or a dynamic delay DEL[3:0]. The delay, if selected, reduces input register hold time requirements when using a global clock.

The input block allows three modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In DDR Mode, two registers are used to sample the data on the positive and negative edges of the DQS signal, creating two data streams, D0 and D1. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-30. Input Register Block Top Edge



Note: Simplified version does not show CE and SET/RESET details.
*On selected blocks.

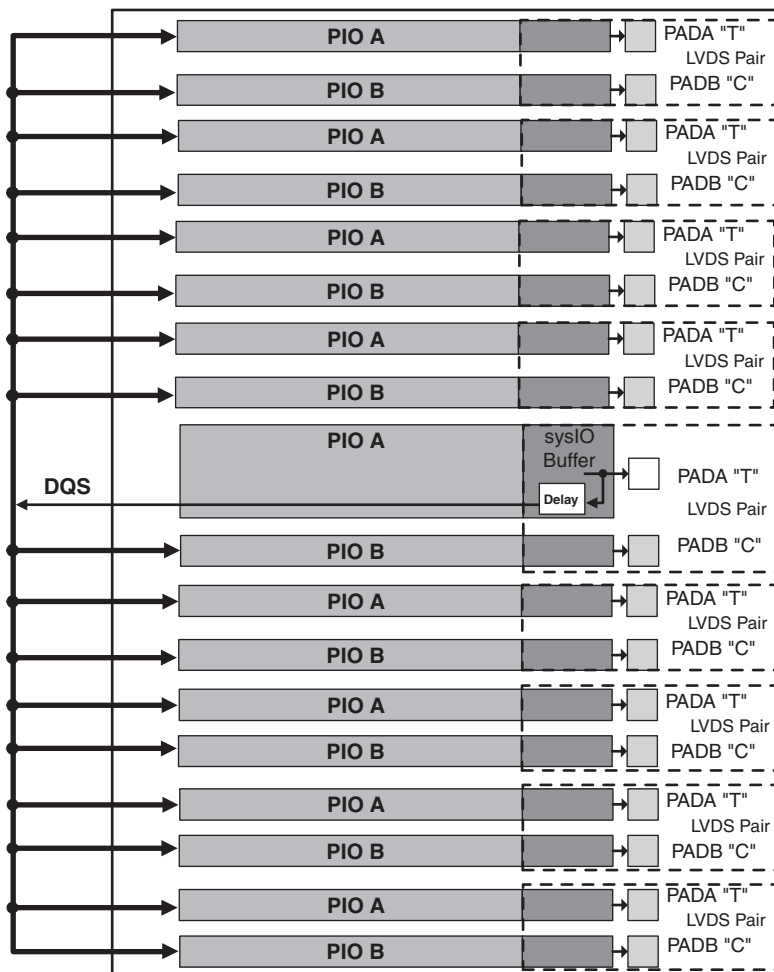
Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysI/O buffers. The blocks on the PIOs on the left, right and bottom contain a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-31 shows the diagram of the Output Register Block for PIOs on the left, right and the bottom edges. Figure 2-32 shows the diagram of the Output Register Block for PIOs on the top edge of the device.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type or latch. In DDR mode, ONEG0 and OPOS0 are fed into registers on the positive edge of the clock. Then at the next clock cycle this registered OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

By combining the output blocks of the complementary PIOs and sharing some registers from input blocks, a gearbox function can be implemented, that takes four data streams: ONEG0A, ONEG1A, ONEG1B and ONEG1B. Figure 2-32 shows the diagram using this gearbox function. For more information about this topic, please see information regarding additional documentation at the end of this data sheet.

Figure 2-34. DQS Input Routing for the Bottom Edge of the Device



DLL Calibrated DQS Delay Block

Source synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However, in DDR memories the clock (referred to as DQS) is not free-running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only, as shown in Figure 2-35) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds polarity control logic, which controls the polarity of the clock to the sync registers in the input register blocks. Figure 2-35 and Figure 2-36 show how the DQS transition signals are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two dedicated DLLs (DDR_DLL) on opposite sides of the device. Each DLL compensates DQS delays in its half of the device as shown in Figure 2-35. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, [LatticeECP2/M sysCONFIG Usage Guide](#) for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. Decryption Support

LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. TransFR (Transparent Field Reconfiguration)

TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#), for details.

3. Dual Boot Image Support

Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 144 TQFP

LFE2-6E/SE					LFE2-12E/12SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
1	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*	
2	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*	
3	PL4A	7		T (LVDS)*	PL4A	7		T (LVDS)*	
4	PL4B	7		C (LVDS)*	PL4B	7		C (LVDS)*	
5	PL6A	7	LDQ10	T (LVDS)*	PL6A	7	LDQ10	T (LVDS)*	
6	VCCAUX	-			VCCAUX	-			
7	PL6B	7	LDQ10	C (LVDS)*	PL6B	7	LDQ10	C (LVDS)*	
8	PL8A	7	LDQ10	T (LVDS)*	PL8A	7	LDQ10	T (LVDS)*	
9	VCCIO7	7			VCCIO7	7			
10	PL8B	7	LDQ10	C (LVDS)*	PL8B	7	LDQ10	C (LVDS)*	
11	GND	-			GND	-			
12	PL12A	7	LDQ10	T (LVDS)*	PL12A	7	LDQ10	T (LVDS)*	
13	PL12B	7	LDQ10	C (LVDS)*	PL12B	7	LDQ10	C (LVDS)*	
14	PL13A	7	PCLKT7_0/LDQ10	T	PL13A	7	PCLKT7_0/LDQ10	T	
15	PL13B	7	PCLKC7_0/LDQ10	C	PL13B	7	PCLKC7_0/LDQ10	C	
16	VCC	-			VCC	-			
17	PL15A	6	PCLKT6_0	T (LVDS)*	PL15A	6	PCLKT6_0	T (LVDS)*	
18	PL15B	6	PCLKC6_0	C (LVDS)*	PL15B	6	PCLKC6_0	C (LVDS)*	
19	PL16A	6	VREF2_6	T	PL16A	6	VREF2_6	T	
20	PL16B	6	VREF1_6	C	PL16B	6	VREF1_6	C	
21	GND	-			GND	-			
22	VCC	-			VCC	-			
23	PL18A	6	LLM0_GDLLT_FB_A	T	PL18A	6	LLM0_GDLLT_FB_A	T	
24	PL18B	6	LLM0_GDLLC_FB_A	C	PL18B	6	LLM0_GDLLC_FB_A	C	
25	LLM0_PLCCAP	6			LLM0_PLCCAP	6			
26	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	
27	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	
28	PL22A	6			PL22A	6			
29	VCC	-			VCC	-			
30	GND	-			GND	-			
31	VCCIO6	6			VCCIO6	6			
32	TCK	-			TCK	-			
33	TDI	-			TDI	-			
34	TDO	-			TDO	-			
35	VCCJ	-			VCCJ	-			
36	TMS	-			TMS	-			
37	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T	
38	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C	
39	VCCAUX	-			VCCAUX	-			
40	PB4A	5	BDQ6	T	PB6A	5	BDQS6	T	
41	PB4B	5	BDQ6	C	PB6B	5	BDQ6	C	
42	VCCIO5	5			VCCIO5	5			
43	PB6A	5	BDQS6	T	PB12A	5	BDQ15	T	
44	PB6B	5	BDQ6	C	PB12B	5	BDQ15	C	
45	NC	5			PB16A	5	BDQ15	T	

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

LFE2-12E/SE					LFE2-20E/SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
92	PB44A	4	BDQ42	T	PB54A	4	BDQ51	T	
93	VCCIO4	4			VCCIO4	4			
94	PB44B	4	BDQ42	C	PB54B	4	BDQ51	C	
95	PB48A	4	BDQ51	T	PB58A	4	BDQ60	T	
96	PB48B	4	BDQ51	C	PB58B	4	BDQ60	C	
97	VCC	-			VCC	-			
98	PB52A	4	BDQ51	T	PB60A	4	BDQS60	T	
99	PB52B	4	BDQ51	C	PB60B	4	BDQ60	C	
100	VCCIO4	4			VCCIO4	4			
101	PB54A	4	BDQ51		PB63A	4	BDQ60		
102	GND	-			GND	-			
103	PB55A	4	VREF2_4/BDQ51	T	PB64A	4	VREF2_4/BDQ60	T	
104	PB55B	4	VREF1_4/BDQ51	C	PB64B	4	VREF1_4/BDQ60	C	
105	CFG1	8			CFG1	8			
106	PROGRAMN	8			PROGRAMN	8			
107	CFG2	8			CFG2	8			
108	INITN	8			INITN	8			
109	CFG0	8			CFG0	8			
110	CCLK	8			CCLK	8			
111	DONE	8			DONE	8			
112	PR29A	8	D0/SPIFASTN		PR43A	8	D0/SPIFASTN		
113	VCCIO8	8			VCCIO8	8			
114	PR26A	8	D6		PR40A	8	D6		
115	GND	-			GND	-			
116	VCC	-			VCC	-			
117	PR25B	8	D7/SPID0	C	PR39B	8	D7/SPID0	C	
118	VCCIO8	8			VCCIO8	8			
119	PR25A	8	DI/CSSPI0N	T	PR39A	8	DI/CSSPI0N	T	
120	PR24B	8	DOU/CSON	C	PR38B	8	DOU/CSON	C	
121	PR24A	8	BUSY/SISPI	T	PR38A	8	BUSY/SISPI	T	
122	GND	-			GND	-			
123	VCCIO3	3			VCCIO3	3			
124	PR21A	3	RLM0_GPLLT_FB_A		PR31A	3	RLM0_GPLLT_FB_A/RDQ34		
125	VCCAUX	-			VCCAUX	-			
126	PR20B	3	RLM0_GPLL_C_IN_A**	C (LVDS)*	PR30B	3	RLM0_GPLL_C_IN_A**/RDQ34	C (LVDS)*	
127	PR20A	3	RLM0_GPLL_T_IN_A**	T (LVDS)*	PR30A	3	RLM0_GPLL_T_IN_A**/RDQ34	T (LVDS)*	
128	RLM0_PLLCAP	3			RLM0_PLLCAP	3			
129	VCC	-			VCC	-			
130	PR18B	3	RLM0_GDLLC_FB_A	C	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C	
131	PR18A	3	RLM0_GDLLT_FB_A	T	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T	
132	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*	
133	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*	
134	PR16B	3	VREF2_3	C	PR22B	3	VREF2_3/RDQ25	C	
135	VCCIO3	3			VCCIO3	3			
136	PR16A	3	VREF1_3	T	PR22A	3	VREF1_3/RDQ25	T	
137	PR15B	3	PCLKC3_0	C (LVDS)*	PR21B	3	PCLKC3_0/RDQ25	C (LVDS)*	

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
J1	J1	PL31A	6	LLM0_GPLLT_FB_A/LDQ34	T
K3	K3	PL30B	6	LLM0_GPLLC_IN_A**/LDQ34	C (LVDS)*
VCCIO	VCCIO	VCCIO6	6		
J2	J2	PL31B	6	LLM0_GPLLC_FB_A/LDQ34	C
GND	GND	GNDIO6	-		
L2	L2	PL38A	6	LDQ42	T (LVDS)*
K2	K2	PL39A	6	LDQ42	T
L3	L3	PL38B	6	LDQ42	C (LVDS)*
K1	K1	PL39B	6	LDQ42	C
VCCIO	VCCIO	VCCIO6	6		
L4	L4	PL40A	6	LDQ42	T (LVDS)*
L1	L1	PL41A	6	LDQ42	T
L5	L5	PL40B	6	LDQ42	C (LVDS)*
M1	M1	PL41B	6	LDQ42	C
GND	GND	GNDIO6	-		
N1	N1	PL43A	6	LDQ42	T
N2	N2	PL42A	6	LDQS42	T (LVDS)*
P1	P1	PL43B	6	LDQ42	C
VCCIO	VCCIO	VCCIO6	6		
P2	P2	PL42B	6	LDQ42	C (LVDS)*
R1	R1	PL44A	6	LDQ42	T (LVDS)*
GND	GND	GNDIO6	-		
R2	R2	PL44B	6	LDQ42	C (LVDS)*
N4	N4	TDI	-		
M4	M4	TCK	-		
P3	P3	TDO	-		
N3	N3	TMS	-		
K7	K7	VCCJ	-		
M5	M5	PB2A	5	VREF2_5/BDQ6	T
K6	K6	PB3A	5	BDQ6	
M6	M6	PB2B	5	VREF1_5/BDQ6	C
R3	R3	PB5A	5	BDQ6	T
P4	P4	PB5B	5	BDQ6	C
-	VCC	VCCIO	5		
-	GND	GNDIO5	5		
N5	N5	PB30A	5	BDQ33	T
N6	N6	PB30B	5	BDQ33	C
T2	T2	PB31A	5	BDQ33	T
P6	P6	PB32A	5	BDQ33	T
VCCIO	VCCIO	VCCIO5	5		
T3	T3	PB31B	5	BDQ33	C
R6	R6	PB32B	5	BDQ33	C

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA

LFE2M20E/SE					LFE2M35E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
D1	PL2A	7	LDQ6	T (LVDS)*	PL2A	7	LDQ6	T (LVDS)*	
E1	PL2B	7	LDQ6	C (LVDS)*	PL2B	7	LDQ6	C (LVDS)*	
F1	PL3A	7	LDQ6	T	PL3A	7	LDQ6	T	
F2	PL3B	7	LDQ6	C	PL3B	7	LDQ6	C	
F5	PL4A	7	LDQ6	T (LVDS)*	PL4A	7	LDQ6	T (LVDS)*	
VCCIO	VCCIO7	7			VCCIO7	7			
G6	PL4B	7	LDQ6	C (LVDS)*	PL4B	7	LDQ6	C (LVDS)*	
F4	PL5A	7	LDQ6	T	PL5A	7	LDQ6	T	
F3	PL5B	7	LDQ6	C	PL5B	7	LDQ6	C	
G1	PL6A	7	LDQS6	T (LVDS)*	PL6A	7	LDQS6	T (LVDS)*	
GNDIO	GNDIO7	-			GNDIO7	-			
G2	PL6B	7	LDQ6	C (LVDS)*	PL6B	7	LDQ6	C (LVDS)*	
H1	PL7A	7	LDQ6	T	PL7A	7	LDQ6	T	
H2	PL7B	7	LDQ6	C	PL7B	7	LDQ6	C	
VCCIO	VCCIO7	7			VCCIO7	7			
H7	PL8A	7	LDQ6	T (LVDS)*	PL8A	7	LDQ6	T (LVDS)*	
H6	PL8B	7	LDQ6	C (LVDS)*	PL8B	7	LDQ6	C (LVDS)*	
G3	PL9A	7	VREF2_7/LDQ6	T	PL9A	7	VREF2_7/LDQ6	T	
H3	PL9B	7	VREF1_7/LDQ6	C	PL9B	7	VREF1_7/LDQ6	C	
GNDIO	GNDIO7	-			GNDIO7	-			
H5	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*	
H4	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*	
J1	PL12A	7	LUM0_SPLLT_FB_A	T	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T	
J2	PL12B	7	LUM0_SPLLC_FB_A	C	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C	
J3	PL13A	7		T (LVDS)*	PL13A	7	LDQ15	T (LVDS)*	
VCCIO	VCCIO7	7			VCCIO7	7			
J4	PL13B	7		C (LVDS)*	PL13B	7	LDQ15	C (LVDS)*	
J7	PL14A	7		T	PL14A	7	LDQ15	T	
J6	PL14B	7		C	PL14B	7	LDQ15	C	
GNDIO	GNDIO7	-			GNDIO7	-			
VCCIO	VCCIO7	7			VCCIO7	7			
K1	PL18A	7	LUM1_SPLLT_IN_A/LDQ22	T (LVDS)*	PL28A	7	LUM1_SPLLT_IN_A/LDQ32	T (LVDS)*	
K2	PL18B	7	LUM1_SPLLC_IN_A/LDQ22	C (LVDS)*	PL28B	7	LUM1_SPLLC_IN_A/LDQ32	C (LVDS)*	
J5	PL19A	7	LUM1_SPLLT_FB_A/LDQ22	T	PL29A	7	LUM1_SPLLT_FB_A/LDQ32	T	
K5	PL19B	7	LUM1_SPLLC_FB_A/LDQ22	C	PL29B	7	LUM1_SPLLC_FB_A/LDQ32	C	
VCCIO	VCCIO7	7			VCCIO7	7			
K7	PL20A	7	LDQ22	T (LVDS)*	PL30A	7	LDQ32	T (LVDS)*	
K6	PL20B	7	LDQ22	C (LVDS)*	PL30B	7	LDQ32	C (LVDS)*	
L6	PL21A	7	LDQ22	T	PL31A	7	LDQ32	T	
L7	PL21B	7	LDQ22	C	PL31B	7	LDQ32	C	
GNDIO	GNDIO7	-			GNDIO7	-			
L1	PL22A	7	LDQS22	T (LVDS)*	PL32A	7	LDQS32	T (LVDS)*	
L2	PL22B	7	LDQ22	C (LVDS)*	PL32B	7	LDQ32	C (LVDS)*	
M7	PL23A	7	LDQ22	T	PL33A	7	LDQ32	T	
VCCIO	VCCIO7	7			VCCIO7	7			
L5	PL23B	7	LDQ22	C	PL33B	7	LDQ32	C	
L3	PL24A	7	LDQ22	T (LVDS)*	PL34A	7	LDQ32	T (LVDS)*	

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
Y6	PB8A	5	BDQ6	T
Y5	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5		
AB3	PB9A	5	BDQ6	T
AB4	PB9B	5	BDQ6	C
AB5	PB10A	5	BDQ6	T
AA6	PB10B	5	BDQ6	C
GNDIO	GNDIO5	-		
VCCIO	VCCIO5	5		
V9	PB40A	5	BDQ42	T
U9	PB40B	5	BDQ42	C
VCCIO	VCCIO5	5		
U10	PB41A	5	BDQ42	T
T10	PB41B	5	BDQ42	C
GNDIO	GNDIO5	-		
W9	PB42A	5	BDQS42****	T
Y8	PB42B	5	BDQ42	C
AA7	PB43A	5	VREF2_5/BDQ42	T
Y7	PB43B	5	VREF1_5/BDQ42	C
AB6	PB44A	5	PCLKT5_0/BDQ42	T
AB7	PB44B	5	PCLKC5_0/BDQ42	C
VCCIO	VCCIO5	5		
GNDIO	GNDIO5	-		
AA8	PB49A	4	PCLKT4_0/BDQ51	T
VCCIO	VCCIO4	4		
AB8	PB49B	4	PCLKC4_0/BDQ51	C
AA9	PB50A	4	VREF2_4/BDQ51	T
Y9	PB50B	4	VREF1_4/BDQ51	C
AB9	PB51A	4	BDQS51****	T
GNDIO	GNDIO4	-		
AB10	PB51B	4	BDQ51	C
AA10	PB52A	4	BDQ51	T
Y11	PB52B	4	BDQ51	C
VCCIO	VCCIO4	4		
GNDIO	GNDIO4	-		
V10	PB56A	4	BDQ60	T
U11	PB56B	4	BDQ60	C
V11	PB57A	4	BDQ60	T
W11	PB57B	4	BDQ60	C
AA11	PB58A	4	BDQ60	T
AB11	PB58B	4	BDQ60	C
VCCIO	VCCIO4	4		
T11	PB59A	4	BDQ60	T

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C12	URC_SQ_VCCIB2	12		
B12	URC_SQ_HDINN2	12		C
C11	URC_SQ_VCCR2	12		
A15	URC_SQ_HDOUTP2	12		T
C15	URC_SQ_VCCOB2	12		
B15	URC_SQ_HDOUTN2	12		C
C14	URC_SQ_VCCTX2	12		
B14	URC_SQ_HDOUTN3	12		C
A13	URC_SQ_VCCOB3	12		
A14	URC_SQ_HDOUTP3	12		T
C13	URC_SQ_VCCTX3	12		
B11	URC_SQ_HDINN3	12		C
B10	URC_SQ_VCCIB3	12		
A11	URC_SQ_HDINP3	12		T
C10	URC_SQ_VCCR3	12		
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
E13	PT55B	1		C
D12	PT55A	1		T
GNDIO	GNDIO1	-		
A9	PT54B	1		C
A8	PT54A	1		T
A7	PT53B	1		C
A6	PT53A	1		T
VCCIO	VCCIO1	1		
E12	PT52B	1		C
F12	PT52A	1		T
A5	PT51B	1		C
A4	PT51A	1		T
GNDIO	GNDIO1	-		
B7	PT50B	1		C
B8	PT50A	1		T
G11	PT49B	1		C
E11	PT49A	1		T
VCCIO	VCCIO1	1		
D11	PT48B	1	VREF2_1	C
D10	PT48A	1	VREF1_1	T
G10	PT47B	1	PCLKC1_0	C
F11	PT47A	1	PCLKT1_0	T
G9	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
F9	PT46A	0	PCLKT0_0	T
C9	PT45B	0	VREF2_0	C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
M10	VCCIO7	7		
M7	VCCIO7	7		
N10	VCCIO7	7		
N3	VCCIO7	7		
P10	VCCIO7	7		
R6	VCCIO7	7		
AA25	VCCIO8	8		
AD28	VCCIO8	8		
AA10	VCCAUX	-		
AA11	VCCAUX	-		
AA20	VCCAUX	-		
AA21	VCCAUX	-		
K10	VCCAUX	-		
K11	VCCAUX	-		
K20	VCCAUX	-		
K21	VCCAUX	-		
L10	VCCAUX	-		
L11	VCCAUX	-		
L20	VCCAUX	-		
L21	VCCAUX	-		
Y10	VCCAUX	-		
Y11	VCCAUX	-		
Y20	VCCAUX	-		
Y21	VCCAUX	-		
A1	GND	-		
A13	GND	-		
A18	GND	-		
A24	GND	-		
A30	GND	-		
A7	GND	-		
AA14	GND	-		
AA15	GND	-		
AA16	GND	-		
AA17	GND	-		
AA24	GND	-		
AA27	GND	-		
AA4	GND	-		
AB24	GND	-		
AB7	GND	-		
AD12	GND	-		
AD19	GND	-		
AD27	GND	-		
AE22	GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
R21	VCC	-			VCC	-		
R22	VCC	-			VCC	-		
T14	VCC	-			VCC	-		
T21	VCC	-			VCC	-		
U14	VCC	-			VCC	-		
U21	VCC	-			VCC	-		
V14	VCC	-			VCC	-		
V21	VCC	-			VCC	-		
W14	VCC	-			VCC	-		
W21	VCC	-			VCC	-		
Y13	VCC	-			VCC	-		
Y14	VCC	-			VCC	-		
Y21	VCC	-			VCC	-		
Y22	VCC	-			VCC	-		
C12	VCCIO0	0			VCCIO0	0		
C16	VCCIO0	0			VCCIO0	0		
E14	VCCIO0	0			VCCIO0	0		
H12	VCCIO0	0			VCCIO0	0		
H16	VCCIO0	0			VCCIO0	0		
M14	VCCIO0	0			VCCIO0	0		
M15	VCCIO0	0			VCCIO0	0		
C19	VCCIO1	1			VCCIO1	1		
C23	VCCIO1	1			VCCIO1	1		
E21	VCCIO1	1			VCCIO1	1		
H19	VCCIO1	1			VCCIO1	1		
H23	VCCIO1	1			VCCIO1	1		
M20	VCCIO1	1			VCCIO1	1		
M21	VCCIO1	1			VCCIO1	1		
G32	VCCIO2	2			VCCIO2	2		
K28	VCCIO2	2			VCCIO2	2		
K32	VCCIO2	2			VCCIO2	2		
N27	VCCIO2	2			VCCIO2	2		
N32	VCCIO2	2			VCCIO2	2		
P23	VCCIO2	2			VCCIO2	2		
R23	VCCIO2	2			VCCIO2	2		
T27	VCCIO2	2			VCCIO2	2		
T32	VCCIO2	2			VCCIO2	2		
AA23	VCCIO3	3			VCCIO3	3		
AB27	VCCIO3	3			VCCIO3	3		
AB32	VCCIO3	3			VCCIO3	3		
AE28	VCCIO3	3			VCCIO3	3		
AE32	VCCIO3	3			VCCIO3	3		
AH32	VCCIO3	3			VCCIO3	3		
W27	VCCIO3	3			VCCIO3	3		
W32	VCCIO3	3			VCCIO3	3		
Y23	VCCIO3	3			VCCIO3	3		
AC20	VCCIO4	4			VCCIO4	4		
AC21	VCCIO4	4			VCCIO4	4		
AG19	VCCIO4	4			VCCIO4	4		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5QN208I	131	1.2V	-5	Lead-Free PQFP	208	IND	20
LFE2-20E-6QN208I	131	1.2V	-6	Lead-Free PQFP	208	IND	20
LFE2-20E-5FN256I	193	1.2V	-5	Lead-Free fpBGA	256	IND	20
LFE2-20E-6FN256I	193	1.2V	-6	Lead-Free fpBGA	256	IND	20
LFE2-20E-5FN484I	331	1.2V	-5	Lead-Free fpBGA	484	IND	20
LFE2-20E-6FN484I	331	1.2V	-6	Lead-Free fpBGA	484	IND	20
LFE2-20E-5FN672I	402	1.2V	-5	Lead-Free fpBGA	672	IND	20
LFE2-20E-6FN672I	402	1.2V	-6	Lead-Free fpBGA	672	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5FN484I	331	1.2V	-5	Lead-Free fpBGA	484	IND	35
LFE2-35E-6FN484I	331	1.2V	-6	Lead-Free fpBGA	484	IND	35
LFE2-35E-5FN672I	450	1.2V	-5	Lead-Free fpBGA	672	IND	35
LFE2-35E-6FN672I	450	1.2V	-6	Lead-Free fpBGA	672	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5FN484I	339	1.2V	-5	Lead-Free fpBGA	484	IND	50
LFE2-50E-6FN484I	339	1.2V	-6	Lead-Free fpBGA	484	IND	50
LFE2-50E-5FN672I	500	1.2V	-5	Lead-Free fpBGA	672	IND	50
LFE2-50E-6FN672I	500	1.2V	-6	Lead-Free fpBGA	672	IND	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5FN672I	500	1.2V	-5	Lead-Free fpBGA	672	IND	70
LFE2-70E-6FN672I	500	1.2V	-6	Lead-Free fpBGA	672	IND	70
LFE2-70E-5FN900I	583	1.2V	-5	Lead-Free fpBGA	900	IND	70
LFE2-70E-6FN900I	583	1.2V	-6	Lead-Free fpBGA	900	IND	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35SE-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	Com	35
LFE2-35SE-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	Com	35
LFE2-35SE-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	Com	35
LFE2-35SE-5FN672C	450	1.2V	-5	Lead-Free fpBGA	672	Com	35
LFE2-35SE-6FN672C	450	1.2V	-6	Lead-Free fpBGA	672	Com	35
LFE2-35SE-7FN672C	450	1.2V	-7	Lead-Free fpBGA	672	Com	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50SE-5FN484C	339	1.2V	-5	Lead-Free fpBGA	484	Com	50
LFE2-50SE-6FN484C	339	1.2V	-6	Lead-Free fpBGA	484	Com	50
LFE2-50SE-7FN484C	339	1.2V	-7	Lead-Free fpBGA	484	Com	50
LFE2-50SE-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	Com	50
LFE2-50SE-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	Com	50
LFE2-50SE-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	Com	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70SE-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	Com	70
LFE2-70SE-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	Com	70
LFE2-70SE-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	Com	70
LFE2-70SE-5FN900C	583	1.2V	-5	Lead-Free fpBGA	900	Com	70
LFE2-70SE-6FN900C	583	1.2V	-6	Lead-Free fpBGA	900	Com	70
LFE2-70SE-7FN900C	583	1.2V	-7	Lead-Free fpBGA	900	Com	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6SE-5TN144I	90	1.2V	-5	Lead-Free TQFP	144	Ind	6
LFE2-6SE-6TN144I	90	1.2V	-6	Lead-Free TQFP	144	Ind	6
LFE2-6SE-5FN256I	190	1.2V	-5	Lead-Free fpBGA	256	Ind	6
LFE2-6SE-6FN256I	190	1.2V	-6	Lead-Free fpBGA	256	Ind	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12SE-5TN144I	93	1.2V	-5	Lead-Free TQFP	144	Ind	12
LFE2-12SE-6TN144I	93	1.2V	-6	Lead-Free TQFP	144	Ind	12
LFE2-12SE-5QN208I	131	1.2V	-5	Lead-Free PQFP	208	Ind	12
LFE2-12SE-6QN208I	131	1.2V	-6	Lead-Free PQFP	208	Ind	12
LFE2-12SE-5FN256I	193	1.2V	-5	Lead-Free fpBGA	256	Ind	12
LFE2-12SE-6FN256I	193	1.2V	-6	Lead-Free fpBGA	256	Ind	12
LFE2-12SE-5FN484I	297	1.2V	-5	Lead-Free fpBGA	484	Ind	12
LFE2-12SE-6FN484I	297	1.2V	-6	Lead-Free fpBGA	484	Ind	12

LatticeECP2M Standard Series Devices, Conventional Packaging
Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5F484C	304	1.2V	-5	fpBGA	484	COM	20
LFE2M20E-6F484C	304	1.2V	-6	fpBGA	484	COM	20
LFE2M20E-7F484C	304	1.2V	-7	fpBGA	484	COM	20
LFE2M20E-5F256C	140	1.2V	-5	fpBGA	256	COM	20
LFE2M20E-6F256C	140	1.2V	-6	fpBGA	256	COM	20
LFE2M20E-7F256C	140	1.2V	-7	fpBGA	256	COM	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5F672C	410	1.2V	-5	fpBGA	672	COM	35
LFE2M35E-6F672C	410	1.2V	-6	fpBGA	672	COM	35
LFE2M35E-7F672C	410	1.2V	-7	fpBGA	672	COM	35
LFE2M35E-5F484C	303	1.2V	-5	fpBGA	484	COM	35
LFE2M35E-6F484C	303	1.2V	-6	fpBGA	484	COM	35
LFE2M35E-7F484C	303	1.2V	-7	fpBGA	484	COM	35
LFE2M35E-5F256C	140	1.2V	-5	fpBGA	256	COM	35
LFE2M35E-6F256C	140	1.2V	-6	fpBGA	256	COM	35
LFE2M35E-7F256C	140	1.2V	-7	fpBGA	256	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5F900C	410	1.2V	-5	fpBGA	900	COM	50
LFE2M50E-6F900C	410	1.2V	-6	fpBGA	900	COM	50
LFE2M50E-7F900C	410	1.2V	-7	fpBGA	900	COM	50
LFE2M50E-5F672C	372	1.2V	-5	fpBGA	672	COM	50
LFE2M50E-6F672C	372	1.2V	-6	fpBGA	672	COM	50
LFE2M50E-7F672C	372	1.2V	-7	fpBGA	672	COM	50
LFE2M50E-5F484C	270	1.2V	-5	fpBGA	484	COM	50
LFE2M50E-6F484C	270	1.2V	-6	fpBGA	484	COM	50
LFE2M50E-7F484C	270	1.2V	-7	fpBGA	484	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5F1152C	436	1.2V	-5	fpBGA	1152	COM	70
LFE2M70E-6F1152C	436	1.2V	-6	fpBGA	1152	COM	70
LFE2M70E-7F1152C	436	1.2V	-7	fpBGA	1152	COM	70
LFE2M70E-5F900C	416	1.2V	-5	fpBGA	900	COM	70
LFE2M70E-6F900C	416	1.2V	-6	fpBGA	900	COM	70
LFE2M70E-7F900C	416	1.2V	-7	fpBGA	900	COM	70

Date	Version	Section	Change Summary
November 2009 (cont.)	03.5 (cont.)	Pinout Information (cont.)	LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100 table - corrected values for LFE2M50, 672 fpBGA in Available DDR-Interfaces per I/O Bank.
			Minor corrections in LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA table.
			Minor corrections in LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA table.
			Minor corrections in LFE2M100E/SE Logic Signal Connections: 900 fpBGA table.
			Updated LFE2-6E/SE and LFE2-12E/SE Logical Signal Connections (changed D1/SPIDS to D1).
		Ordering Information	Updated LatticeECP2M Part Number Description diagram.
March 2010	03.6	DC and Switching Characteristics	Footnote for SED operating frequency added to the sysCONFIG Port Timing Specifications table.
		Pinout Information	Changed Dual Function pin E7 to be D7/SPDI0 in Logic Signal Connections tables. Changed footnote (***) in Logic Signal Connections table.
July 2010	03.7	Architecture	Updated the Typical sysIO Behavior During Power-up text section.
		Pinout Information	Added reference to powerup information.
			Corrected reference to footnote for pins 131 and 132 for the LFE-20E/SE, 208 PQFP.
			Referenced footnote (***) for all D7/SPID0.
			Changed D7*** to D7/SPID0.
			Corrected *** footnote.
		All Sections	Included references to Lattice Diamond design software wherever ispLEVER and ispLeverCORE is specified.
April 2011	03.8	DC and Switching Characteristics	DC Electrical Characteristics table: - Added footnote 3 to I_{IH} - Added footnote 2 to I_{IL} , I_{IH} - Updated C1 and C2 typ. and max. data.
			DLL Timing table – Removed line for t_R and t_F
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added footnote to t_{DINIT} .
			Figure 3-18 – Corrected label to be PRGM (not PRGMRJ).
		Pinout Information	LFE2-12E/SE and LFE-20/SE Logical Signal Connections for 208 PQFP – Corrected Dual Function information for pins 112, 114, 117, 119.
January 2012	03.9	Multiple	Removed references to ispLEVER design software.
		Architecture	Corrected information regarding SED support.
		DC and Switching Characteristics	Added reference to ESD information.
June 2013	04.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.